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 - (7) external factors (abnormal voltage, abnormal electromagnetic wave, fire, etc.)

(8) special environment (factory, coastal areas, hotspring area, etc.)

(9) phenomenon which cannot be foreseen based on the practical technologies at the time of shipment.

(10) the factors not included in the product specification sheet.

4. Please contact and consult with a Sharp sales representative for any questions about Sharp product.

1. Application

This technical sheets applies to the outline and characteristics of time of flight sensor Model No. GP2AP02VT00F

- 2. Outline Refer to the drawing page 7.
- 3. Ratings and characteristics Refer to the attached sheet, Page 8 to 9.
- 4. Reliability Refer to the attached sheet, Page 10.
- 5. Outgoing inspection Refer to the attached sheet, Page 11.
- 6. Supplement
 - 1) This product is built-in SPAD (single photon avalanche diode).
 - 2) Brominated flame retardants

Specific brominated flame retardants such as the PBB and PBDE are not used in this device at all.

3) This product shall not contain the following materials.

Also, the following materials shall not be used in the production process for this product.

Materials for ODS : CFCs, Halon, Carbon tetrachloride, 1,1,1-Trichloroethane (Methylchloroform)

4) Compliance with each regulation

- 4.1) This product complies with EU RoHS Directive (2011/65/EU) and Commission Delegated Directive (EU)2015/863)
- 4.2) Content of six substances specified in Management Methods for Control of Pollution Caused by Electronic
 - Information Products Regulation (Chinese: 电子信息产品污染控制管理力法).

Category	Lead (Pb)	Mercury (Hg)	Cadmium (Cd)	Hexavalent chromium (Cr ⁶⁺)	Polybrominated biphenyls (PBB)	Polybrominated diphenyl ethers (PBDE)
Time of flight sensor	0	0	0	0	0	0

Marking Styles for the Names and Contents of the Hazardous Substances

This table is prepared in accordance with the provisions of SJ/T 11364.

○ : Indicates that said hazardous substance contained in all of the homogeneous materials for this part is

below the limit requirement of GB/T 26572

- 5) Country of origin: China
- 6) Product mass : Approx . 0.028g
- 7) The moisture absorption level of this product is MSL.3.

8) Taping specifications : Refer to the attached sheet, Page 13 to 15.

9) Taping moisture-proof packing; Refer to the attached sheet, Page 16 to 18.

10) Eye Safety Considerations

GP2AP02VT00F contains a laser emitter and corresponding drive circuitry. The laser output is Class 1 laser safety under all reasonably foreseeable including single faults in compliance with IEC 60825-1:2014. The laser output will remain within Class 1 limits as long as the Sharp recommended device settings are used and the operating conditions specified in this datasheet are respected. The laser output power must not be increased by any means and no optics should be used with the intention of focusing the laser beam. List of controls, adjustments and procedures for operation and maintenance, including the warning "Caution - Use of controls or adjustments or performance of procedures other than those specified herein may result in hazardous radiation exposure" (or alternatively, equivalent appropriate wanings).



VDDV

GPIO

EN

VDD

7. Notes

1) Notes concerning receiver surface

Please note enough that it is likely to malfunction when a surface is dirty with garbage and dust, etc. Moreover, please do not touch a surface.

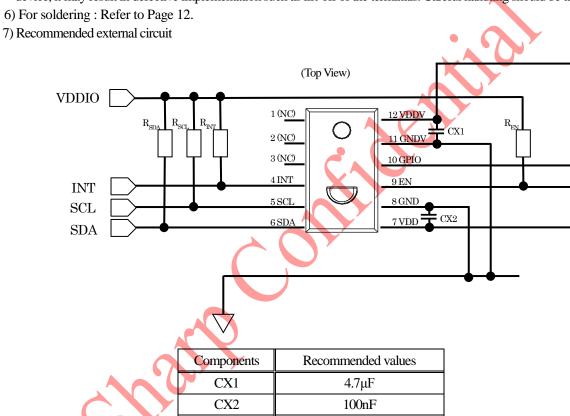
- 2) Please take proper methods to prevent ESD. The IC built in GP2AP02VT00F is ESD-sensitive because it is fabricated by sub-micron CMOS process. For example, in handling GP2AP02VT00F, human body and soldering iron etc. should be grounded.
- 3) Before the circuit design

In circuit designing, make allowance for the degradation of the laser output that results from long continuous operation.

4) Notes ambient light

When set to avoid malfunctions due to a strong disturbance light, such an arrangement to receive ambient light directly on the detector, please be avoided. Also by placing this product in close to other components, it may be a malfunction with the light reflected from their product, structural arrangement to reduce the amount of light receiving surface of the outer, please consider.

- 5) After being mounted and soldered, if GP2AP02VT00F is deformed by external force or impact, e.g. something falls onto the device, it may result in defective implementation such as lift-off of the terminals. Careful handling should be taken.
- 6) For soldering : Refer to Page 12.



There are cases to generate a noise because VCSEL driving current flows VDDV terminal, and to distort a waveform of VCSEL driving current.

R_{SDA*1}

R_{SCL*1}

RINT

 R_{EN}

1~10kΩ

1~10kΩ

 $47k\Omega$

 $47k\Omega$

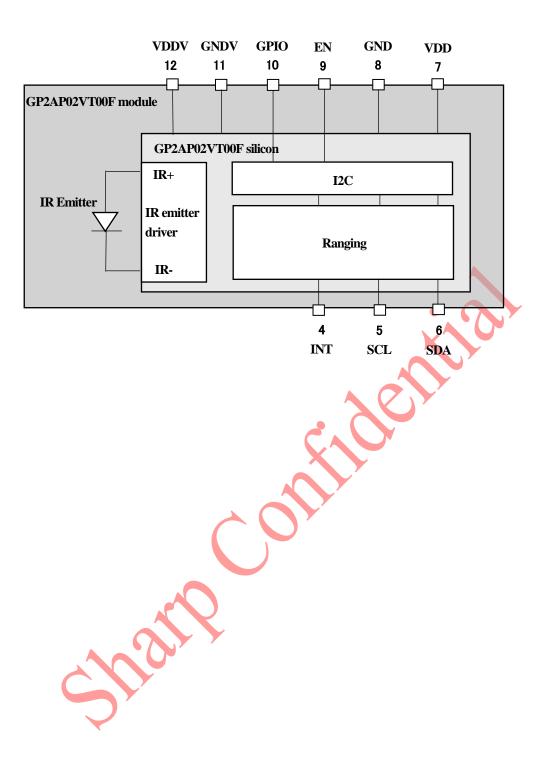
To reduce these influences, please arrange CX1 within 5mm from VDDV terminal, and wire between VDDV terminal, CX1 and GND terminal as close as possible. Also, the wiring of VDDV is separated from VDD and VDDIO terminals, and the power source of VDDV is separated from VDD is recommended.

And in order to reduce the influence of the power supply noise, please arrange CX2 within 5mm from VDD terminal. Please evaluate with the actual electrical implementation, and carefully make sure that there is no problem.

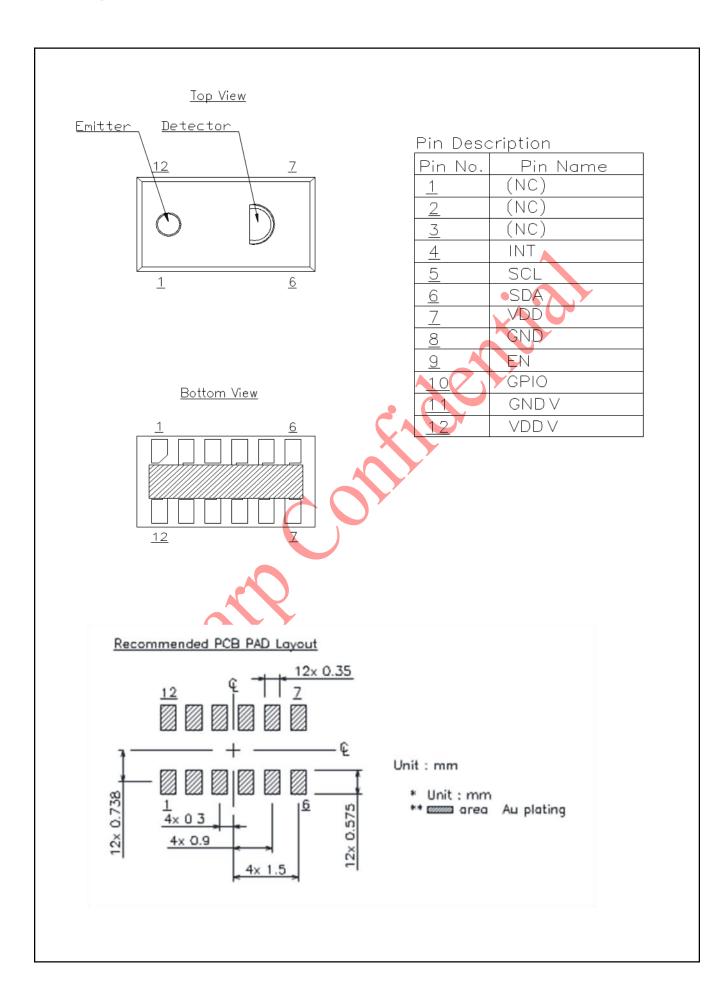
SDA and GPIO terminal is NMOS open-drain output and digital input. EN and SCL terminals are digital input. INT terminal is NMOS open-drain output.

*1 The pull-up resistor needs to be adjusted by communication speed, board capacitance, power supply voltage.

8) Block diagram



9) Foot pattern of PCB

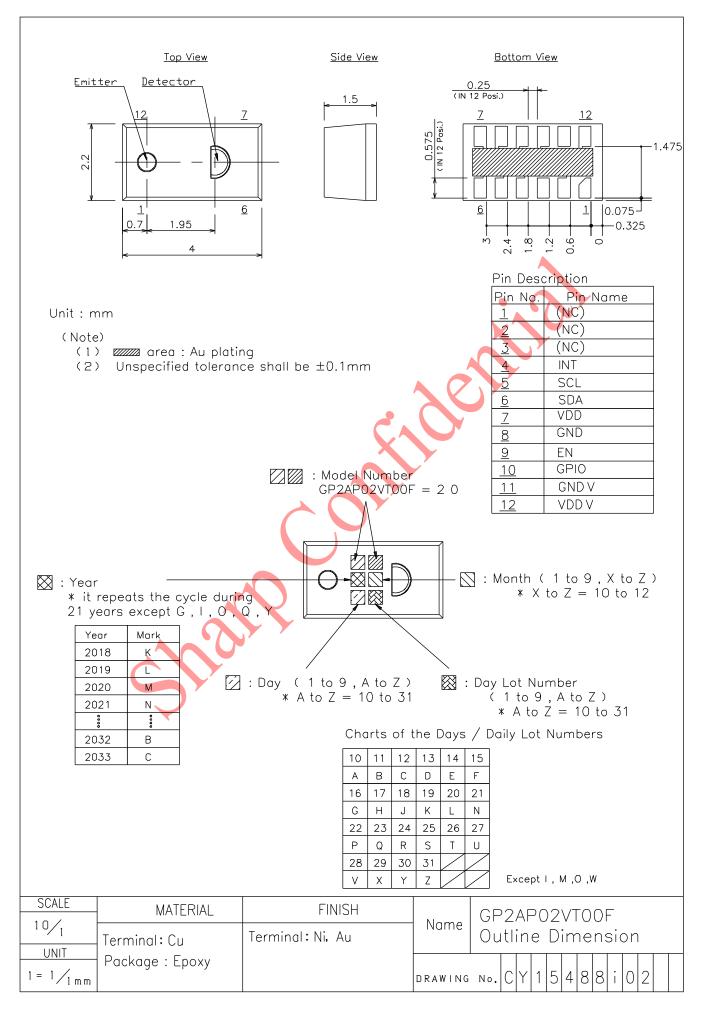


10) Pin Description

Pin Name	Functional description	Equivalent Internal Circuit
VDD	Power Supply	O VDD
VDD	Tower Suppry	
		O GND
VDDV	VCSEL Dower Supply	O VDDV
VDD V	VCSEL Power Supply	
		O GNDV
GND	Ground	O GNDV
GNDV	VCSEL Ground	
		╡ <u></u>
		O GND
SDA	I2C serial data line	VDDIO
SDA	12C seriai data inte	VDDCORE
	The terminal is pulled-up to VDDIO	
		SDA
	<u> </u>	VDD <u>IO</u>
SCL	I2C serial clock line	
	The terminal is pulled-up to VDDIO	Internal Regulater
	The terminal is punce-up to VDDIO	
		O GND
INT	Interrupt pin	
		Internal
	The terminal is pulled-up to VDDIO	Regulater
	Open drain output terminal	
		O GND
EN	Enable pin	VDDIO
EIN	The terminal is pulled-up to VDDIO	Internal
		Reaulater
		O GND
		○ —•
GPIO	GPIO pin	Internal Reaulater
		configurable_
		*ESD protection device

*ESD protection device

2. Outline Dimensions



3. Ratings and Characteristics

3.1 Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit	Remarks
Power supply voltage	VDD	-0.5 to 3.6	V	
VCSELvoltage	VDDV	-0.5 to 3.6	V	
I2C voltage	VDDIO	-0.5 to 3.6	V	
Operating temperature	Topr	-20 to 70	°C	
Storage temperature	Tstg	-40 to 85	°C	
Soldering temperature	Tsol	250	°C	peak temperature duration:10s

3.2 Recommended Operating Conditions

Symbol	Operating condition	Unit	Remarks
VDD	2.6 to 3.5	V	
VDDV	2.6 to 3.5	V	
VDDIO	1.7 to 3.5	V	
Topr	-20 to 70	°C	
Tfunc	-20 to 70	°C	
VIL	-0.25 to 0.5	V	
VIH	1.3 to VDDIO+0.15	V	
VILIO	-0.25 to 0.5	V	
VIHIO	1.3 to VDDIO+0.15	V	
	VDD VDDV VDDIO Topr Tfunc VIL VIL VIH VILIO	VDD 2.6 to 3.5 VDDV 2.6 to 3.5 VDDIO 1.7 to 3.5 VDDIO 1.7 to 3.5 Topr -20 to 70 Tfunc -20 to 70 VIL -0.25 to 0.5 VIH 1.3 to VDDIO+0.15 VILIO -0.25 to 0.5	VDD 2.6 to 3.5 V VDDV 2.6 to 3.5 V VDDV 2.6 to 3.5 V VDDIO 1.7 to 3.5 V Topr -20 to 70 °C Tfunc -20 to 70 °C VIL -0.25 to 0.5 V VIH 1.3 to VDDIO+0.15 V VILIO -0.25 to 0.5 V

3.3 Electrical and Optical Characteristics

3.3.1 Electrical Characteristics

Ta=25°C, VDD=VDDV=VDDIO=3.3V

(Unless otherwise specified, the external circuit constants follow the recommended external circuit of page 3.)							
Parameter	Symbol	Min.	Тур.	Max.	Unit	Remarks	
Current consumption (Short mode)	I _{CC_ps}		1.7	_	mA	80 ms cycle	
Current consumption (Long mode)	I _{CC_dis}	\mathbf{r}	10		mA	33 ms cycle	
Current consumption (Power Down)	I _{CC-S}		_	10	μΑ		
I2C clock frequency	f	1	-	1000	kHz		
SDA output low level voltage	Vol_sda	0	-	0.4	V	I _{OL_SDA} =3mA	
INT output low level voltage	Vol_int	0	_	0.4	V	I _{OL_INT} =3mA	

3.3.2 VCSEL Characteristics

Ta=25°C, VDD= VDDV=VDDIO =3.3V

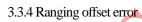
(Unless otherwise specified,	the extern	al circuit	constants	follow the	recommen	ded external circuit of page 3.)
Parameter	Symbol	Min.	Тур.	Max.	Unit	Remarks
VCSEL peak wavelength	λ_{P_PS}	—	940	—	nm	
VCSEL peak current	Ivcselp	—	31	—	mA	Short mode
VCSEL peak current	Ivcseld	—	64	-	mA	Long mode
VCSEL FOV	Fov		25	—	0	

3.3.3	Ranging	Characteristics
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Ta=25°C, VDD=VDDV=VDDIO=3.3V

(Unless otherwise specified,	(Unless otherwise specified, the external circuit constants follow the recommended external circuit of page 3.)							
Parameter	Symbol	Min.	Тур.	Max.	Unit	Remarks		
Range distance (Short mode : 100mm)	Rinw1	-10	—	+10	mm	IF=31mA,White 88%		
Repeatability (Short mode : 100mm)	Rinrepw1	0	-	+10	mm	Indoor : no infrared		
Range distance (Long mode : 100mm)	Rinw1	-10	-	+10	mm	IF=64mA,White 88%		
Repeatability (Long mode : 100mm)	Rinrepw1	0		+10	mm	Indoor : no infrared		
Range distance (Long mode : 1200mm)	Ring2	-4		+4	%	IF=64mA,White 88%		
Repeatability (Long mode : 1200mm)	Rinrepg2	0		+25	mm	Indoor : no infrared		
Range distance (Long mode : 700mm)	Ring3	-5	_	+5	%	IF=64mA,Gray 17%		
Repeatability (Long mode : 700mm)	Rinrepg3	0		+25	mm	Indoor : no infrared		
Range distance (Outdoor, Long mode : 700mm)	Routw	-10	_	+10	%	White 88%		
Repeatability (Outdoor, Long mode :700mm)	Routw	0	_	+25	mm	Equivalent to 50kLux daylight		
Ranging speed	Trange	_	33		msec	400kHz,Normal mode		
Min ranging distance (Short mode)	Rinsmin			50	mm	IF=31mA,White 88% Indoor∶no infrared		
Min ranging distance (Long mode)	Rinlmin		•	100	mm	IF=64mA,White 88% Indoor : no infrared		
Max ranging distance (Long mode, gray card)	Ringmax	120	X	-	cm	IF=64mA,Gray 17% Indoor : no infrared		
Mode changing to Short mode	Shortth		80	_	mm			
Mode changing to Long mode	Longth		100	—	mm			
		V						

* Repeatability : max – min (10 times evaluation)



(Unless otherwise specified, the external circuit constants follow the recommended external circuit of page 3.)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Remarks
Voltage drift	Vdrift	_		10	mm	Ta=25°C, VDD=VDDV=VDDIO =3.2~3.4V
Temperature drift (Range Average)	Tdrift	_	_	15	mm	Ta=-10°C~+60°C, VDD=VDDV=VDDIO=3.3V

4. Reliability

The reliability of products shall satisfy items listed below.

		Confidence l	evel : 90% TPD : 10 or 20
Test Items	Test Condition	Failure Judgment Criteria	<u>Samples (n)</u> Defective (C)
* Temperature cycling	1 cycle -40°C(30min) to +85°C(30min) 20 cycles test	$I_{CC_VDD} > U_P \times 1.2$ Up: Upper	n=22, c=0
*High temp. and high humidity storage	+60°C, 90%RH, 240h	specification limit	n=22, c=0
* High temp. storage	+85°C, 240h	Range accuracy <-10% Range accuracy >+10%	n=22, c=0
*Low temp. storage	-40°C, 240h	Condition: VDD=VDDV=VDDIO	n=22, c=0
Operation life	+25°C, VDD=VDDV=VDDIO=3.6V, 240h	=2.8V, Gray Card 17%, Indoor at 600mm	n=11, c=0
Mechanical shock	1000m/s ² , 6ms 3 times / \pm X, \pm Y, \pm Z direction		n=22, c=0
Variable frequency vibration	200m/s ² 100 to 2000 to 100Hz/ Approx. for 4min 48 min/ X, Y, Z direction		n=22, c=0
Reflow solder heat	250°C, 10s, three times. Temperature profile as shown in page 12.		n=22, c=0

In the test *mark above, the sample to be tested shall be left at normal temperature and humidity for 2h after it is taken out of the chamber. (No dew point)

These test results are sampling examples from a specific lot for reference purpose only, and do not constitute any warranty or assurance in connection with the products.



5. Outgoing inspection

(1) Inspection lot

Inspection shall be carried out per each delivery lot.

(2) Inspection method

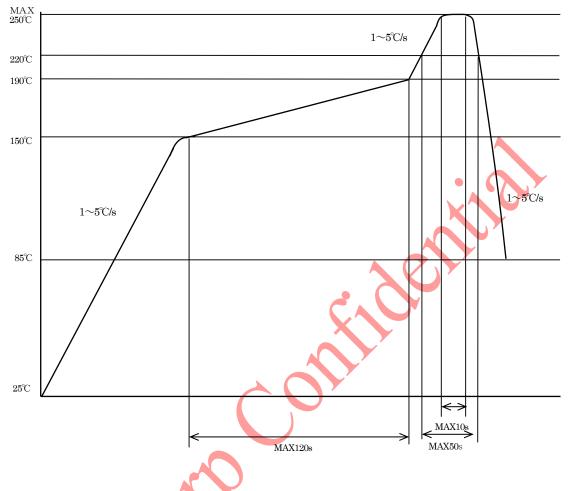
A single sampling plan, normal inspection level II based on ISO 2859 shall be adopted.

Parameter		AQL(%)				
Major	1. Disconnection, sh	ort	0.1			
defect	2. Electrical characte	0.1				
	Appearance defect					
Minor	Parameter	Judgment criteria				
defect	Cracks, Chipping,	One which affects the characteristics of	0.25			
ucieet	Scratches,	Parameter 3.3 shall be defect.				
	Stains, Burrs	r aaneer 5,5 shan be dereet.				
Ç						

Precautions for Soldering

(1)In case of solder reflow

Reflow is allowed only three at the temperature and the time within the temperature profile as shown in the figure below. This Profile temperature is the sensor surface package temperature. Reflow interval shall be within 7days under conditions, 10 to 30°C, 70%RH or less.



(2)Other precautions

An infrared lamp used to heat up for soldering may cause a localized temperature rise in the resin of package inside. Even if within the temperature profile above, there is the possibility that the gold wire in package is broken. Please use after confirmation the conditions fully actual solder reflow machine.

1. Application

This packing specification sheets specify the taping specifications for GP2AP02VT00F.

- 2. Taping method
 - 2.1. Tape structure and Dimensions (Refer to page 14.)

The tape shall have a structure in which a cover tape is sealed pressed on the carrier tape of conductive Polycarbonate.

2.2.Reel structure and Dimensions (Refer to page 15.)

The taping reel shall be conductive plastic with its dimensions as shown in the attached drawing.

2.3.Direction of product insertion (Refer to page 15.)

The sensor direction in carrier tape shall be; the detector of the sensor locates to the feeding hole side of the carrier tape and the sensor window faces to the top of the pocket of the carrier tape.

2.4. The way to repair taped failure devices

The way to repair taped failure devices cut a bottom of carrier tape with a cutter, and after replacing to good devices, the cutting portion shall be sealed with adhesive tape.

3. Adhesiveness of cover tape

The exfoliation force between carrier tape cover tape shall be 0.2N to 1.2N for the angle from 160 degrees to 180 degrees.

4. Rolling method and quantity

Wind the tape back on the reet so that the cover tape will be outside the tape. Attach 16cm or more of blank tape to the trailer and 40cm or more of blank tape to the leader and fix the both ends with adhesive tape. One reel shall contain 2,000pcs. Except for the case that device is removed. There must not be continuously two or more Stock-Outs.

5. Safety protection during shipping

There shall be no deformation of component or degradation of electrical characteristics due to shipping.

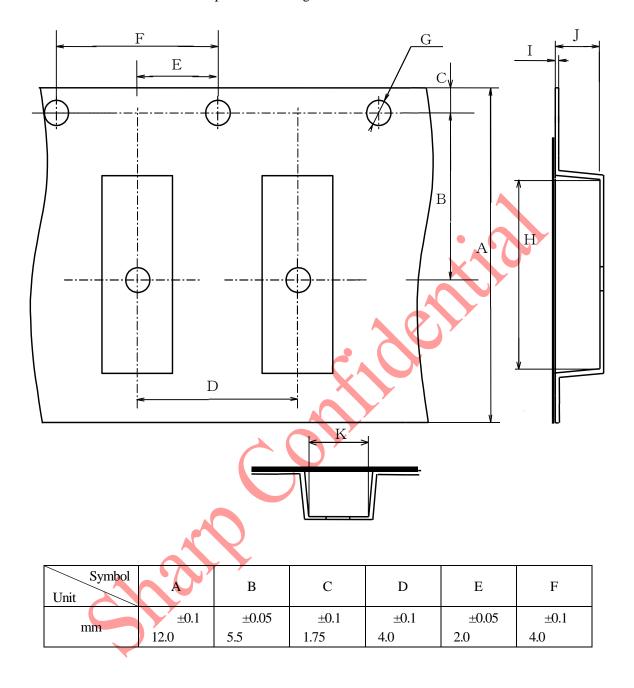
6. Surface resistivity

Name	Surface resistivity $(\Omega \land \Box)$	Material
Carrier tape	1×10^4 to 1×10^8	Electroconductive polycarbonate
Cover tape	1×10^4 to 1×10^7	Poly ethylene terephthalate
Reel	Less than 1×10^9	Poly phenylene ether

7. Tape and Real structures

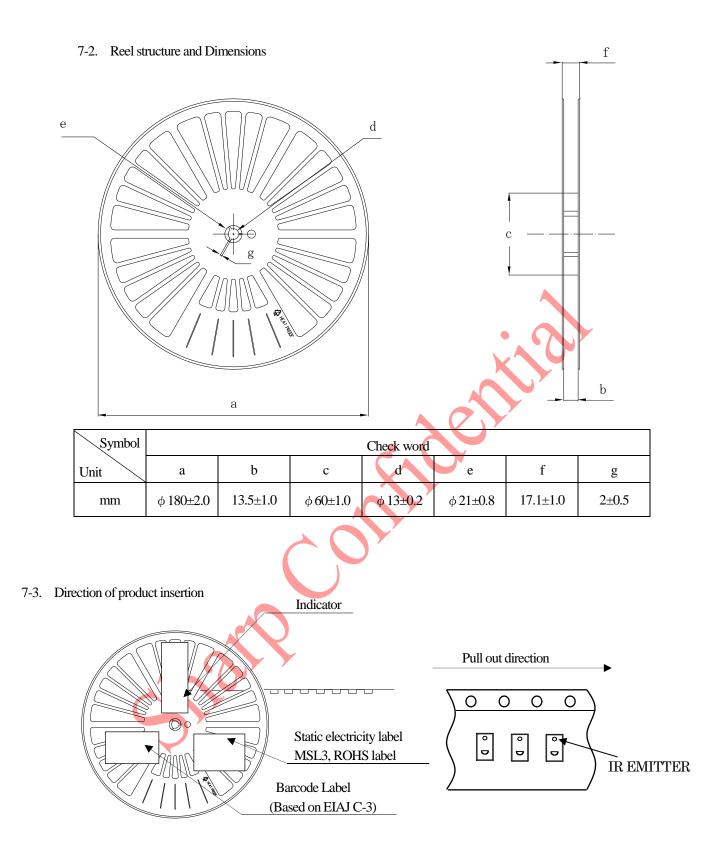
7.1 Tape structure and Dimensions

Tape outline drawing



Symbol Unit	G	Н	Ι	J	K
mm	+0.1 -0	±0.1	±0.05	±0.1	±0.1
	Φ1.5	4.25	0.28	1.75	2.45

GP2AP02VT00F



Taping moisture-proof packing

1. Application

This packing specification sheets apply to the moist-proof packing for the GP2AP02VT00F in the taping package.

2. Packaging specifications

2.1 Packaging material

Name	Material	Counter measure for ESD	Quantity
Aluminum laminate bag	Aluminum polyethylene	Conductive type	
Label	Paper(-made)	Non	
Siccative	-	Non	Defende 22
Packing case	Paper	Non	Refer to 2.2
Cushioning material	Urethane	Non	
Indicator	Paper	Non	

2.2 Packaging method

- (1) Fill necessary information to barcode labels.
- (2) Paste one of the barcode labels and a moisture indicator to a tape reel (contains 2,000 devices per reel).
- (3) Seal the aluminum laminated bag that contains the tape reel and siccative, and paste one of the barcode labels.
- Pack 5 aluminum laminated bags (contains 1 reel each) into the designated packing case, where Urethane cushioning material are placed on the top of the packing case.

Package shape	Product	Quantity	Moisture-proof sack Quantity
Tape reel (ϕ 180mm)	1 model	2000pcs. / reel *	1 reel / laminated bag

(5) The packing case would be then sealed with the craft tape, with barcode label (based on EIAJ C-3).
 (Total of 10,000pcs. per carton) * Except for the case that device is removed.

3. Storage and Treatment after Unsealed

3.1 Storage conditions The delivered product should be stored with the conditions shown below;

Storage temperature : 10 to 30°C

Humidity : below 70% RH

The warranty term for the shipped product shall be for 1 year after shipping to the designated place by the ordered customer.

3.2 Treatment after open

- (1) After unsealed, devices should be mounted under the temperature condition of 10 to 30°C, at the humidity condition of below 70% RH, within 7 days.
- (2) In case that long term storage is needed, devices should either be stored in dry box, or re-sealed to moist-proof bag with siccative and leave them in the environment where the temperature is 10 to 30°C, at the humidity condition of below 70% RH. Devices must be mounted within 2 weeks.
- 3.3 Baking before mounting

In the event that the devices are not maintained in the storage conditions described above, or the enclosed siccative indicator already turned its color to light-green, baking must be applied before devices are to be mounted.

The case that Devices were not mounted under the temperature condition of 10 to 30° C at the humidity

condition of below 70% RH or lower within 7 days, Baking process must be applied before devices are to be mounted.: Please also note that baking should only be applied twice.

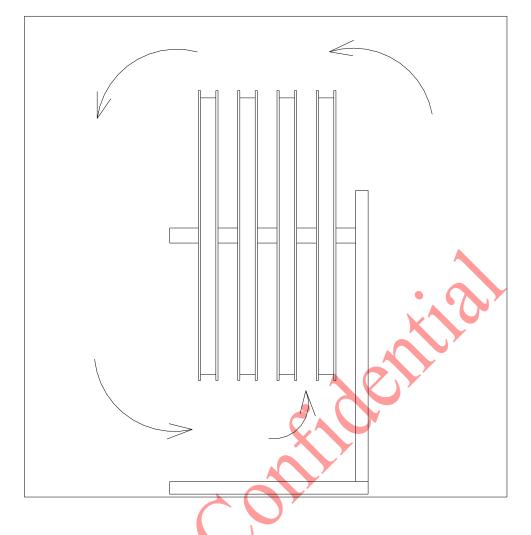
Recommended condition : (1)100 to 110° C, 12 to 24 hours $(2)125^{\circ}$ C, 6 to 24 hours

* Baking will not properly done in packing condition.

To complete the baking properly, devices should be placed to the metal tray.

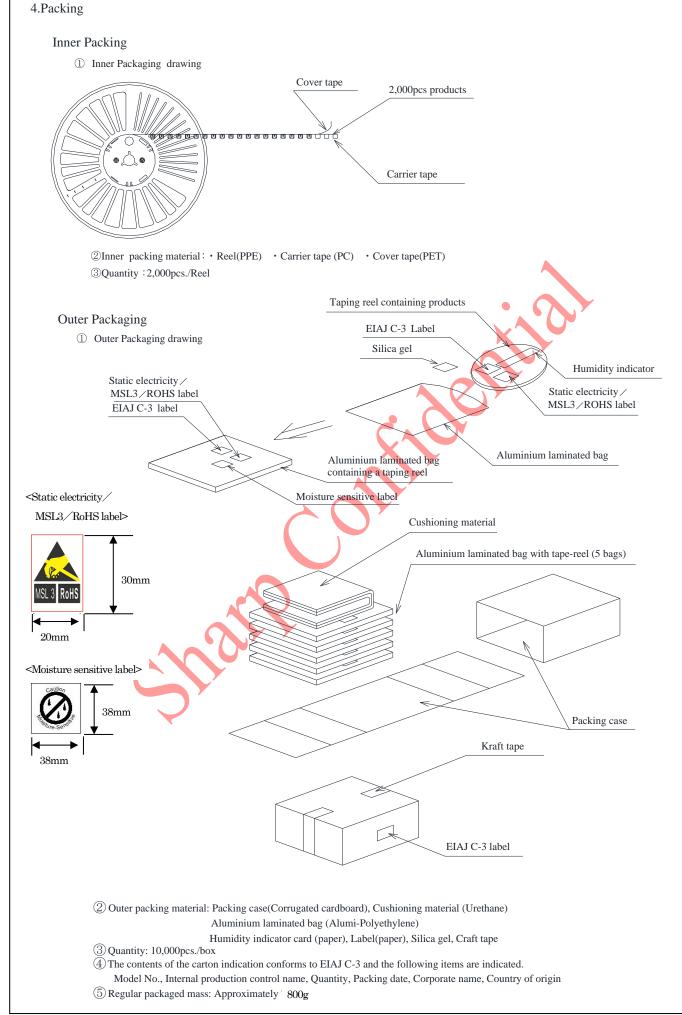
- Recommended condition of reel baking :125°C, 6 to 24hours
- ※ In the case of reel baking, hung the reel in the oven by passing the shaft in the center hole of reel.
 Please avoid laying the reel.

3.4 Placement of reels in an oven



- Please hang reels by using a center hole for fixing the reel.
 Please keep some space between reels for better air rotation in the oven.
 Please do not lay a reel down in the oven to avoid any damages for the tape edge and the flange of reel.
- 2) Please make sure the carrier tape does not have any slack in a reel before baking to avoid peeling the cover tape off.

Since the tape using for fixing carrier tape is not heatproof, there is a case to remain glue. So if necessary, please change the tape to a heatproof one.



8. Revision History

	Description	Date
0.0	Preliminary release	12-Jan-2018
0.1	Change of electrical characteristics	30-Apr-2018
0.2	Change the pull-up register.(RSDA, RSCL)	30-May-2018
0.3	P3 - GPIO terminal delete pull-up resister	28-June-2018
	P6 - 10) Pin description GPIO terminal	28-June-2018
	P8-9) VDD condition	28-June-2018
0.4	3.3 Electrical and Optical Characteristic	12-July-2018
0.5	P2 Eye Safety Considerations	2-Aug-2018
0.6	3.3 Electrical and Optical Characteristic (outdoor)	7-Aug-2018
0.7	P3,5,7 Outline dimensions P.2 EU RoHS Comments, Product mass P.14 Tape outline drawing P.18 Regular package mass	22-Jan-2019
0.8	3. Ratings and Characteristics	1-Feb-2019
0.9	3. Ratings and Characteristics7. Tape and Real structures	15-April-2019
1.0	3. Ratings and Characteristics4. Packing	25-July-2019
1.1	All. "Confidential" etc. delete 4. Packing " Huawei" delete	26-Aug-2019
1.2	 Outline Dimensions Notes 	22-Nov-2019
1.3	 Outline Dimensions Ratings and Characteristics Notes Taping specifications Tape and Real structures 	25-Nov-2019